

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.52403	100.0	10.18
			Subtotal	0.52403	100	10.18
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.66714	100.0	12.96
			Subtotal	0.66714	100	12.96
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01616	5.0	0.314
	Lead alloy	Silver (Ag)	7440-22-4	0.00808	2.5	0.157
	Lead alloy	Lead (Pb)	7439-92-1	0.29903	92.5	5.809
			Subtotal	0.32327	100	6.28
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.38988	100.0	27
			Subtotal	1.38988	100	27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02726	0.04	0.52948
	Copper alloy	Iron (Fe)	7439-89-6	0.06814	0.1	1.3237
	Copper alloy	Copper (Cu)	7440-50-8	68.04454	99.86	1,321.84682
			Subtotal	68.13994	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.51915	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.63292	16.0	90
	Filler	Silica fused	60676-86-0	21.71681	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.08687	0.3	1.6875
			Subtotal	28.95575	100	562.5
			Total	100.00001	100	NaN

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